



1 NOTE:  
020122MR008□□25ZA

1. Selective plating  
 \*S1,-05u" Min. gold in contact area/  
 100u" Min. Tin in solder area.  
 \*S2,-Gold flash in contact area/  
 100u" Min. Tin in solder area.  
 \*S3,-10u" Min. gold in contact area/  
 100u" Min. Tin in solder area.  
 \*S4,-15u" Min. gold in contact area/  
 100u" Min. Tin in solder area.  
 \*S5,-30u" Min. gold in contact area/  
 100u" Min. Tin in solder area.  
 \*S6,-50u" Min. gold in contact area/  
 100u" Min. Tin in solder area.

NO.	DESCRIPTION	MATERIAL	COLOR	REMARK
6	SHELL	Brass	—	NICK PLATED
5	SHELL	Brass	—	NICK PLATED
4	SHELL	Brass	—	NICK PLATED
3	TERMINAL	Pho.Bronze	—	GOLD/TIN
2	BACK-CAP	LCP	BLACK	UL 94V-0
1	HOUSING	LCP	BLACK	UL 94V-0

**SUYIN**  
CONNECTOR

CUSTOMER COPY TITLE: USB Series A Type Dual Port Dip Type

ECN (DCN) NO.	REV	DATE	DESCRIPTION	CHANGE	APPRO.	GENERAL TOLERANCE UNLESS OTHERWISE NOTED	APPRO.	SCALE	UNIT	mm	A4	⊕			
EC1T-021114-07	C	02/11/14	D1:增加新料號	宋勃逸	宋權哲	Angle 30 ±2°	DRAW	薛梅	2002/04/02	PART NO.	020122MR008SX25ZA ⊕				
EC1T-020808-07	B	02/08/08	C1:增加偷料孔; C2, C3:修改鐵殼彈片	薛梅	宋權哲	10 ~ 30 ±0.30	DESIGN	薛梅	2002/04/02	PART NO. (OLD)	2522AY-08XXX-Y				
EC1T-020701-04	A	02/07/01	恢復撕破處 取消撕破處	薛梅	周孫宇	~ 10 ±0.15	CHECK	宋權哲	2002/04/02	DRAWING NO.	020122MR008SX25ZA				
							APPRO.	宋權哲	2002/04/02	SCALE	4:1	UNIT	mm	A4	⊕